

**AMENDMENTS TO THE SPECIFICATION:**

Please **amend the paragraph beginning on page 2, line 21**, as follows:

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b1 It is the object of the present invention to provide, in a substrate section of the kind mentioned in the ~~introductory part of Claim 1~~ beginning hereof, an embodiment of the carrier layer provided in a releasing aid, by means of which embodiment the leaking-out of pressure-sensitive adhesive in cold flow can be prevented easily and with simple means, thus facilitating easy withdrawal of substrate sections from a package which is open only at one side.

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